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16-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

Check for Samples: SN74AVCB164245-Q1

FEATURES

- Qualified for Automotive Applications
- Member of the Texas Instruments Widebus™ Family
- DOC[™] Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCB} Voltage
- If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Ioff Supports Partial-Power-Down Mode
 Operation
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over Full 1.4-V to 3.6-V Power-Supply Range
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 750-V Charged-Device Model (C101)

DESCRIPTION

This 16-bit (dual-octal) noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCB164245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCB164245 is designed so that the control pins (1DIR, 2DIR, 1 \overline{OE} , and 2 \overline{OE}) are supplied by V_{CCB}.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CCB} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either V_{CC} input is at GND, both ports are in the high-impedance state.

ORDERING INFORMATION⁽¹⁾

T _A	PACK	(AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	TSSOP – DGG	Tape and reel	CAVCB164245QDGGRQ1	AVCB164245Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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TERMINAL ASSIGNMENTS

DGG PACKAGE
(TOP VIEW)

			_	1
1DIR	1	U	48	
1B1	2		47] 1A1
1B2	3		46	1A2
GND	4		45	GND
1B3	5		44	1A3
1B4 🛛	6		43] 1A4
V _{CCB}	7		42	V _{CCA}
1B5	8		41] 1A5
1B6 🛛	9		40] 1A6
GND	10		39	GND
1B7 🛛	11		38] 1A7
1B8 🛛	12		37] 1A8
2B1 🛛	13		36	2A1
2B2	14		35	2A2
GND [15		34] GND
2B3 🛛	16		33	2A3
2B4 🛛	17		32	2A4
V _{CCB}	18		31	V _{CCA}
2B5	19		30	2A5
2B6 🛛	20		29	2A6
GND [21		28] GND
2B7 🛛	22		27] 2A7
2B8 🛛	23		26	2A8
2DIR	24		25] 2 <u>0E</u>
l				

FUNCTION TABLE (EACH 8-BIT SECTION)

UTS	OPERATION
DIR	OPERATION
L	B data to A bus
Н	A data to B bus
Х	Isolation
	DIR L

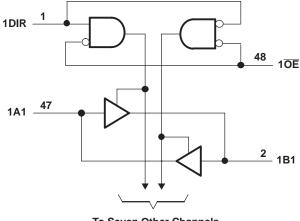
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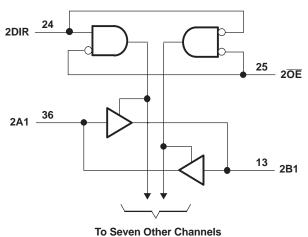
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LOGIC DIAGRAM (POSITIVE LOGIC)





To Seven Other Channels

Pin numbers shown are for the DGG and DGV packages.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CCA} V _{CCB}	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
V	Voltage range applied to any output in the high-impedance or power-off	A port	-0.5	4.6	V
Vo	state ⁽²⁾	B port	-0.5	4.6	v
V	Veltage range employed to any extruct in the high or law state $\binom{2}{3}$	A port	-0.5	V _{CCA} + 0.5	V
Vo	Voltage range applied to any output in the high or low state $^{(2)}$ $^{(3)}$	B port	-0.5	V _{CCB} + 0.5	v
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V _{CCA} , V _{CCB} , or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package		70	°C/W
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

ÈXAS INSTRUMENTS

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Recommended Operating Conditions^{(1) (2) (3)}

over operating free-air temperature range (unless otherwise noted)

			V _{CCI}	V _{cco}	MIN	MAX	UNIT
V_{CCA}	Supply voltage				1.4	3.6	V
V _{CCB}	Supply voltage				1.4	3.6	V
			1.4 V to 1.95 V		V _{CCI} × 0.65		
V _{IH}	High-level input voltage	Data inputs	1.95 V to 2.7 V		1.7		V
			2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			$V_{CCI} \times 0.35$	
VIL	Low-level input voltage	Data inputs	1.95 V to 2.7 V			0.7	V
			2.7 V to 3.6 V			0.8	
			1.4 V to 1.95 V		$V_{CCB} \times 0.65$		
VIH	High-level input voltage	Control inputs (referenced to V _{CCB})	1.95 V to 2.7 V		1.7		V
		(referenced to VCCB) -	2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			V _{CCB} × 0.35	
V _{IL}	Low-level input voltage	Control inputs (referenced to V _{CCB})	1.95 V to 2.7 V			0.7	V
		(referenced to v CCB) =	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
V	Output voltage	Active state			0	V _{cco}	V
Vo	Oulput voltage	3-state			0	3.6	v
				1.4 V to 1.6 V		-2	
	Llich lovel output ourrent			1.65 V to 1.95 V		-4	mA
I _{OH}	High-level output current			2.3 V to 2.7 V		-8	ШA
				3 V to 3.6 V		-12	
				1.4 V to 1.6 V		2	
	Low lovel output ourrent			1.65 V to 1.95 V		4	A
I _{OL}	Low-level output current			2.3 V to 2.7 V		8	mA
				3 V to 3.6 V		12	
Δt/Δv	Input transition rise or fall	rate				5	ns/V
T _A	Operating free-air temperation	ature			-40	125	°C

(1)

 V_{CCI} is the V_{CC} associated with the data input port. V_{CCO} is the V_{CC} associated with the data output port. All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. (2) (3)



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Electrical Characteristics⁽¹⁾ ⁽²⁾

over operating free-air temperature range (unless otherwise noted)

	AMETER	TEST CONDI		v	v		-40°C to		T _A = -	40°C to '	125°C	UNIT
PAP	AWEIER	TEST CONDI		V _{CCA}	V _{CCB}	MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX	UNII
		I _{OH} = -100 μA	$V_{I} = V_{IH}$	1.4 V to 3.6 V	1.4 V to 3.6 V	V _{CCO} - 0.2			V _{CCO} - 0.2			
		I _{OH} = -2 mA	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			1.05			
V _{OH}		$I_{OH} = -4 \text{ mA}$	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			1.2			V
		I _{OH} = -8 mA	$V_{I} = V_{IH}$	2.3 V	2.3 V	1.75			1.75			
		I _{OH} = -12 mA	$V_{I} = V_{IH}$	3 V	3 V	2.3			2.3			
		I _{OH} = 100 μA	$V_{I} = V_{IL}$	1.4 V to 3.6 V	1.4 V to 3.6 V			0.2			0.2	
		$I_{OH} = 2 \text{ mA}$	$V_{I} = V_{IL}$	1.4 V	1.4 V			0.35			0.35	
V _{OL}		I _{OH} = 4 mA	$V_{I} = V_{IL}$	1.65 V	1.65 V			0.45			0.45	V
		I _{OH} = 8 mA	$V_{I} = V_{IL}$	2.3 V	2.3 V			0.55			0.55	
		I _{OH} = 12 mA	$V_{I} = V_{IL}$	3 V	3 V			0.7			0.7	
lı	Control inputs	$V_{I} = V_{CCB}$ or GND		1.4 V to 3.6 V	3.6 V			±2.5			±2.5	μA
1	A port			0 V	0 to 3.6 V			±10			±10	
off	B port	$V_{\rm I}$ or $V_{\rm O}$ = 0 to 3.6 V		0 to 3.6 V	0 V			±10			±10	μA
. (4)	A or B ports	$V_0 = V_{CCO}$ or GND,	$\overline{OE} = V_{IH}$	3.6 V	3.6 V			±12.5			±12.5	
I _{OZ} ⁽⁴⁾	B port	$V_{I} = V_{CCI} \text{ or GND}$	$\overline{OE} = don't$	0 V	3.6 V			±12.5			±12.5	μA
	A port		care	3.6 V	0 V			±12.5			±12.5	
				1.6 V	1.6 V			20			35	
				1.95 V	1.95 V			20			35	
				2.7 V	2.7 V			30			45	
CCA		$V_I = V_{CCI}$ or GND,	$I_0 = 0$	0 V	3.6 V			-40			-50	μA
				3.6 V	0 V			40			50	
				3.6 V	3.6 V			40			50	
				1.6 V	1.6 V			20			35	
				1.95 V	1.95 V			20			35	
		$V_{I} = V_{CCI}$ or GND,	1 - 0	2.7 V	2.7 V			30			45	
ССВ		$v_{I} = v_{CCI} \cup U \cup U$	1 ₀ = 0	0 V	3.6 V			40			50	μA
				3.6 V	0 V			-40			-50	
				3.6 V	3.6 V			40			50	
Ci	Control inputs	$V_1 = 3.3 \text{ V or GND}$		3.3 V	3.3 V		4			4		pF
C _{io}	A or B ports	V_{O} = 3.3 V or GND		3.3 V	3.3 V		5			5		pF

(1)

 V_{CCO} is the V_{CC} associated with the output port. V_{CCI} is the V_{CC} associated with the input port. All typical values are at T_A = 25°C. For I/O ports, the parameter I_{OZ} includes the input leakage current. (2) (3) (4)



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Switching Characteristics

 T_{A} = -40°C to 85°C, V_{CCA} = 1.5 V ± 0.1 V (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = 1 ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	А	В	1.7	6.7	1.9	6.3	1.8	5.5	1.7	5.8	5
t _{pd}	В	А	1.8	6.8	2.2	7.4	2.1	7.6	2.1	7.3	ns
	OE	А	2.5	8.4	2.4	7.4	2.1	5.2	1.9	4.2	5
t _{en}	OE	В	2.1	9	2.9	9.8	3.2	10	3	9.8	ns
	OE	A	2.2	6.9	2.3	6.1	1.3	3.6	1.3	3	20
t _{dis}	OE	В	2.1	7.1	2.3	6.4	1.7	5.1	1.6	4.8	ns

Switching Characteristics

 $T_A = -40^{\circ}C$ to 125°C, $V_{CCA} = 1.5 \text{ V} \pm 0.1 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	-	-	TO	V _{ССВ} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
		(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
+	А	В	1.7	12.7	1.9	12.3	1.8	11.5	1.7	11.8			
t _{pd}	В	А	1.8	12.8	2.2	13.4	2.1	13.6	2.1	13.3	ns		
	OE	А	2.5	14.4	2.4	13.4	2.1	11.2	1.9	10.2			
t _{en}	ÛE	В	2.1	15	2.9	15.8	3.2	16	3	15.8	ns		
	OE	А	2.2	12.9	2.3	12.1	1.3	9.6	1.3	9	20		
t _{dis}	ÛE	В	2.1	13.1	2.3	12.4	1.7	11.1	1.6	10.8	ns		

Switching Characteristics

 $T_A = -40^{\circ}C$ to 85°C, $V_{CCA} = 1.8$ V ± 0.15 V (see Figure 2)

PARAMETER	FROM (INPUT)	-	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
		(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
	А	В	1.7	6.7	1.8	6	1.7	4.7	1.6	4.3	~~	
t _{pd}	В	А	1.4	5.5	1.8	6	1.8	5.8	1.8	5.5	ns	
	OE	А	2.6	8.5	2.5	7.5	2.2	5.3	1.9	4.2	~~	
t _{en}	0E	В	1.8	7.6	2.6	7.7	2.6	7.6	2.6	7.4	ns	
	OE	А	2.3	7	2.3	6.1	1.3	3.6	1.3	3	~~	
t _{dis}	0E	В	1.8	7	2.5	6.3	1.8	4.7	1.7	4.4	ns	

Switching Characteristics

 T_{A} = -40°C to 125°C, V_{CCA} = 1.8 V \pm 0.15 V (see Figure 2)

PARAMETER	FROM (INPUT)	-	TO (OUTPUT)	V _{ССВ} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
		(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
	А	В	1.7	12.7	1.8	12	1.7	10.7	1.6	10.3	20	
t _{pd}	В	А	1.4	11.5	1.8	12	1.8	11.8	1.8	11.5	ns	
	OE	А	2.6	14.5	2.5	13.5	2.2	11.3	1.9	10.2	20	
t _{en}	0E	В	1.8	13.6	2.6	13.7	2.6	13.6	2.6	13.4	ns	
t _{dis} <u>OE</u>		А	2.3	13	2.3	12.1	1.3	9.6	1.3	9	20	
t _{dis}	0E	В	1.8	13	2.5	12.3	1.8	10.7	1.7	10.4	ns	



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Switching Characteristics

 $T_A = -40^{\circ}C$ to 85°C, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	-	-	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
		(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
	А	В	1.6	6	1.8	5.6	1.5	4	1.4	3.4	5		
t _{pd}	В	А	1.3	4.6	1.7	4.4	1.5	4	1.4	3.7	ns		
	OE	А	3.1	8.5	2.5	7.5	2.2	5.3	1.9	4.2	5		
t _{en}	ÛE	В	1.7	5.7	2.2	5.5	2.2	5.3	2.2	5.1	ns		
	OE	А	2.4	7	3	6.1	1.4	3.6	1.2	3	5		
t _{dis}	0E	В	1.2	5.8	1.9	5	1.4	3.6	1.3	3.3	ns		

Switching Characteristics

 T_{A} = -40°C to 125°C, V_{CCA} = 2.5 V \pm 0.2 V (see Figure 2)

PARAMETER	FROM	TO	V _{ССВ} = ± 0.1		V _{CCB} = 1 ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
+	А	В	1.6	12	1.8	11.6	1.5	10	1.4	9.4	20
t _{pd}	В	А	1.3	10.6	1.7	10.4	1.5	10	1.4	9.7	ns
	OE	А	3.1	14.5	2.5	13.5	2.2	11.3	1.9	10.2	20
t _{en}	UE	В	1.7	11.7	2.2	11.5	2.2	11.3	2.2	11.1	ns
	OE	А	2.4	13	3	12.1	1.4	9.6	1.2	9	5
t _{dis}	UE	В	1.2	11.8	1.9	11	1.4	9.6	1.3	9.3	ns

Switching Characteristics

 $T_A = -40^{\circ}C$ to 85°C, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (see Figure 2)

PARAMETER	FROM	TO	V _{CCB} = ± 0.1		V _{CCB} = 1 ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	А	В	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	20
t _{pd}	В	А	1.3	4.5	1.6	3.8	1.5	3.3	1.4	3.1	ns
	OE	А	2.6	8.3	2.5	7.4	2.2	5.2	1.9	4.1	20
t _{en}	0E	В	1.6	4.9	2	4.5	2	4.3	1.9	4.1	ns
	OE	А	2.3	7	3	6	1.3	3.5	1.2	3.5	20
t _{dis}	0E	В	1.3	6.9	2.1	5.5	1.6	3.8	1.5	3.5	ns

Switching Characteristics

 T_{A} = -40°C to 125°C, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 2)

PARAMETER	FROM	TO	V _{ССВ} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	МАХ	
	А	В	1.5	11.9	1.7	11.4	1.5	9.7	1.4	9.1	20
t _{pd}	В	А	1.3	10.5	1.6	9.8	1.5	9.3	1.4	9.1	ns
	OE	А	2.6	14.3	2.5	13.4	2.2	11.2	1.9	10.1	20
t _{en}	ÛE	В	1.6	10.9	2	10.5	2	10.3	1.9	10.1	ns
t _{dis}	OE	А	2.3	13	3	12	1.3	9.5	1.2	9.5	20
	OE	В	1.3	12.9	2.1	11.5	1.6	9.8	1.5	9.5	ns

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Operating Characteristics

 V_{CCA} and $V_{CCB} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT		
	Power dissipation capacitance per transceiver,	Power dissipation capacitance per transceiver. Outputs enabled				
C _{pdA}	A-port input, B-port output	Outputs disabled		7	- F	
C _{pdA} (V _{CCA})	Power dissipation capacitance per transceiver,	Outputs enabled	$C_{L} = 0, f = 10 \text{ MHz}$	20	pF	
	B-port input, A-port output	Outputs disabled		7		
	Power dissipation capacitance per transceiver,	Outputs enabled		20		
C _{pdB}	A-port input, B-port output	Outputs disabled		7	~ F	
C _{pdB} (V _{CCB})	Power dissipation capacitance per transceiver,	Outputs enabled		14	pF	
	B-port input, A-port output	Outputs disabled		7		

Output Description

The DOCTM circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOCTM) Circuitry Technology and Applications*, literature number SCEA009.

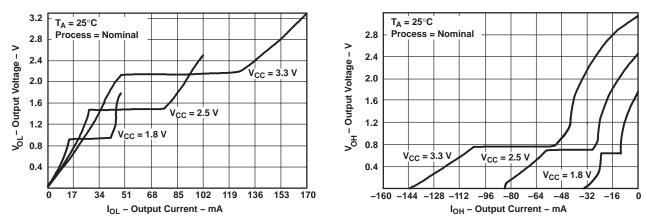
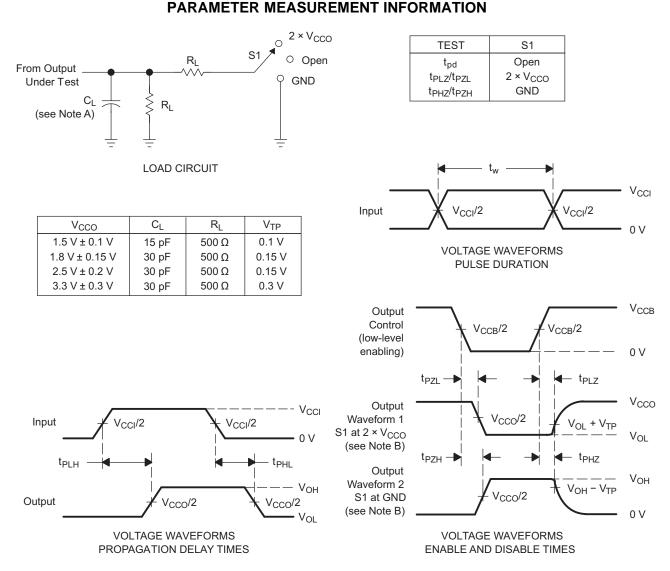


Figure 1. Typical Output Voltage vs Output Current



SN74AVCB164245-Q1

SCES809A - MARCH 2010-REVISED MAY 2010



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, $Z_0 = 50 \Omega$, $dv/dt \ge 1 V/ns$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.

Figure 2. Load Circuit and Voltage Waveforms



11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
CAVCB164245QDGGRQ1	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	AVCB164245Q	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74AVCB164245-Q1 :

• Catalog: SN74AVCB164245



PACKAGE OPTION ADDENDUM

11-Apr-2013

Enhanced Product: SN74AVCB164245-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAVCB164245QDGGRQ1	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

16-Mar-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CAVCB164245QDGGRQ1	TSSOP	DGG	48	2000	367.0	367.0	45.0

MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153

